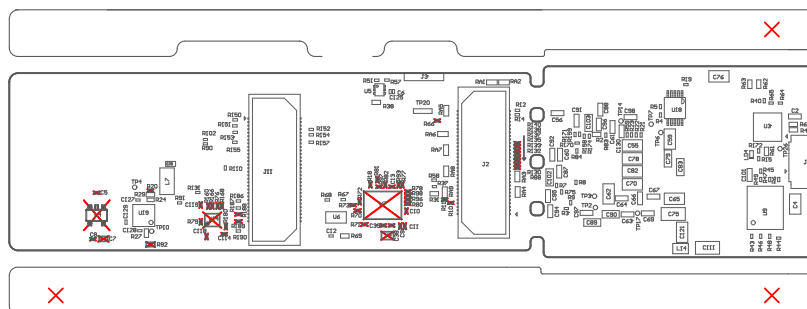


- 221 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- 222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- 223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- 224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- 225.1 ■ Cut the thermal pad (Part Number #GPUOUS-0.125-AC-DB16) for the shape and size of the inner surface of the heatsink (Part Number #MCH065) and paste it on the inner surface of the heatsink;
- 225.2 ■ Bring the heatsink onto the PCB bottom side (Opposite side of AOP device). Match the teeth in the heatsink with break-away area in the PCB and press the heatsink onto the PCB slightly so as thermal pad is spread all over the area

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PROC106	REV: A1	SUN REV: Not In VersionControl
M5 Assembly Top	TID #: N/A		
PLOT NAME = Top Assembly Drawing	GENERATED : 03-03-2021 15:02:52		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PROC106	REV: A1	SUN REV: Not In VersionControl
	TID #: N/A	M6 Assembly Bottom	
PLOT NAME = Bottom Assembly Drawing	GENERATED : 03-03-2021	15:02:53	TEXAS INSTRUMENTS

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (<https://www.ti.com/legal/termsofsale.html>) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2021, Texas Instruments Incorporated